

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/652,534
Priority Filing Date August 31, 2000
Inventor Sujit Sharan et al.
Assignee Micron Technology, Inc.
Priority Group Art Unit 2823
Priority Examiner Trung Q. Dang
Attorney's Docket No. MI22-2360
TITLE: Plasma Enhanced Chemical Vapor Deposition Methods and Semiconductor
Processing Methods of Forming Layers and Shallow Trench Isolation Regions

Assistant Commissioner for Patents
Washington, D. C. 20231
Attention: Official Draftsman


SUBSTITUTE DRAWING REQUEST

Please enter the enclosed substitute drawings in the above-referenced application in place of drawings originally filed. The content of the drawings are identical to those now on file in this application.

Acknowledgment of receipt of the formal drawings and their acceptance into the file is requested.

Respectfully submitted,

Date: 7-16-03

By: 
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Enclosures: Sheets of Formal Drawings, Figs. 1-6.